

FIG. 1

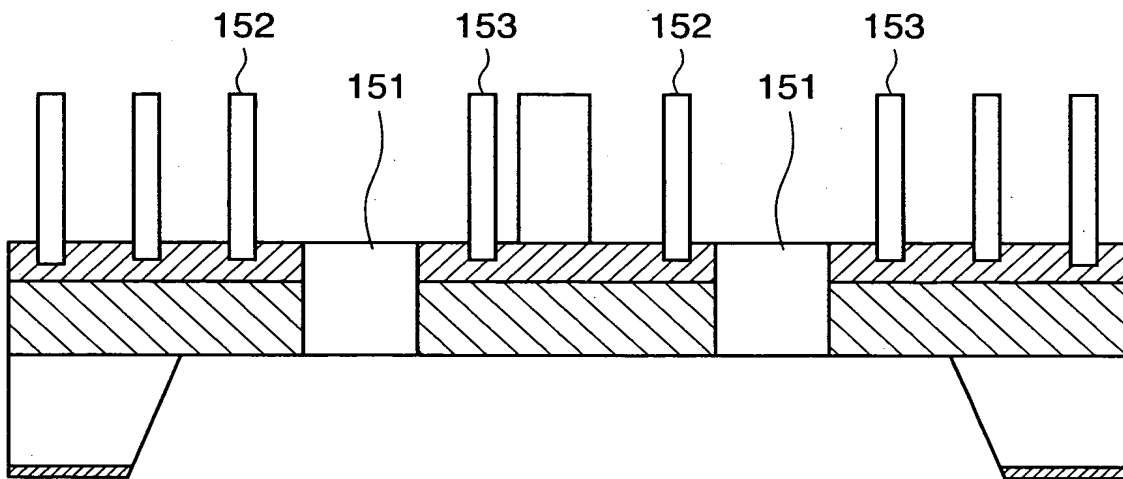


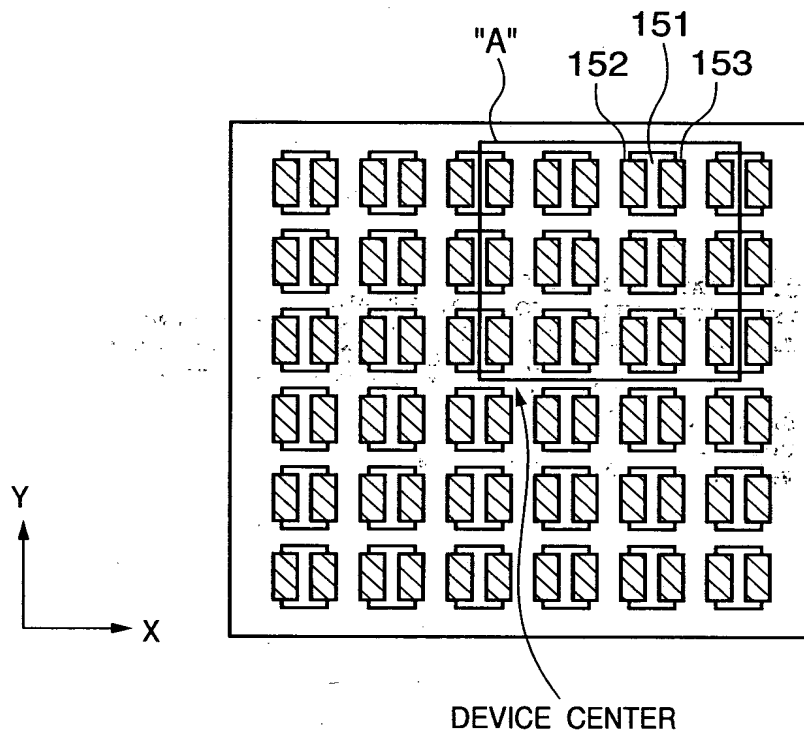
FIG. 2

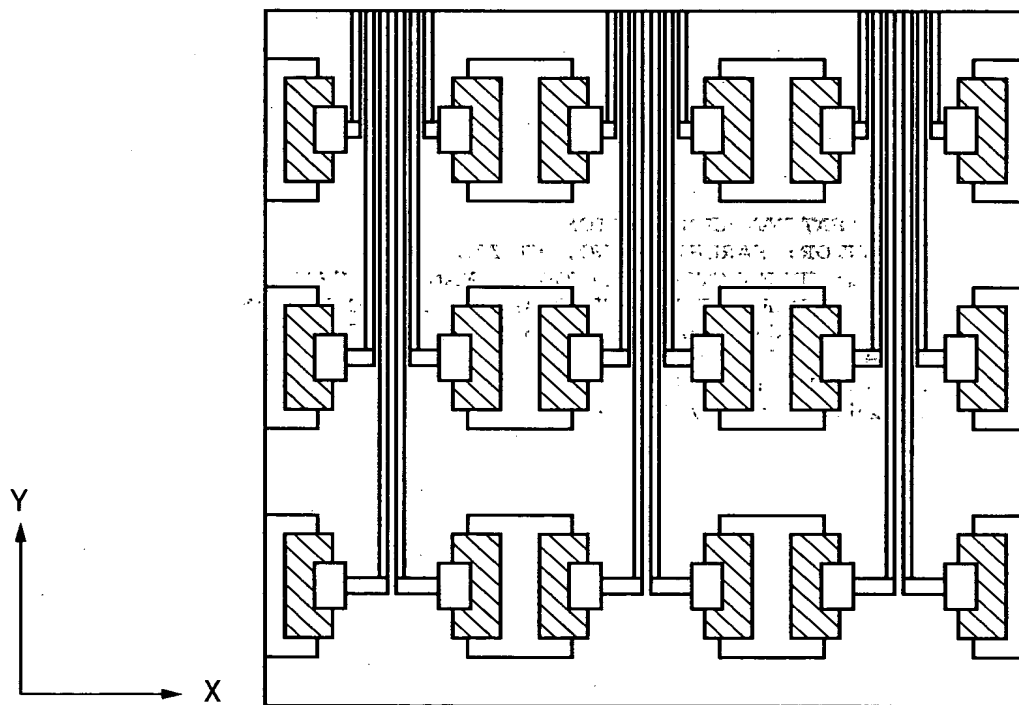
FIG. 3

FIG. 4A

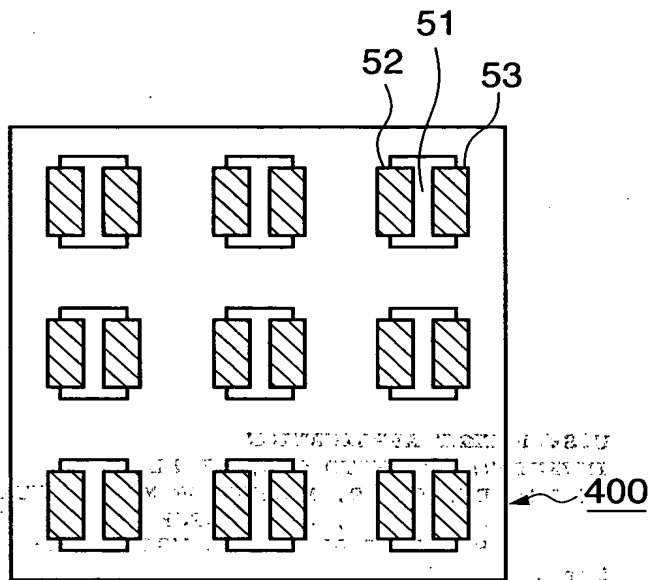


FIG. 4B

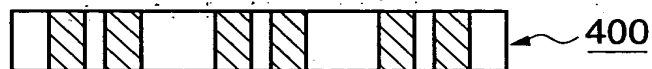


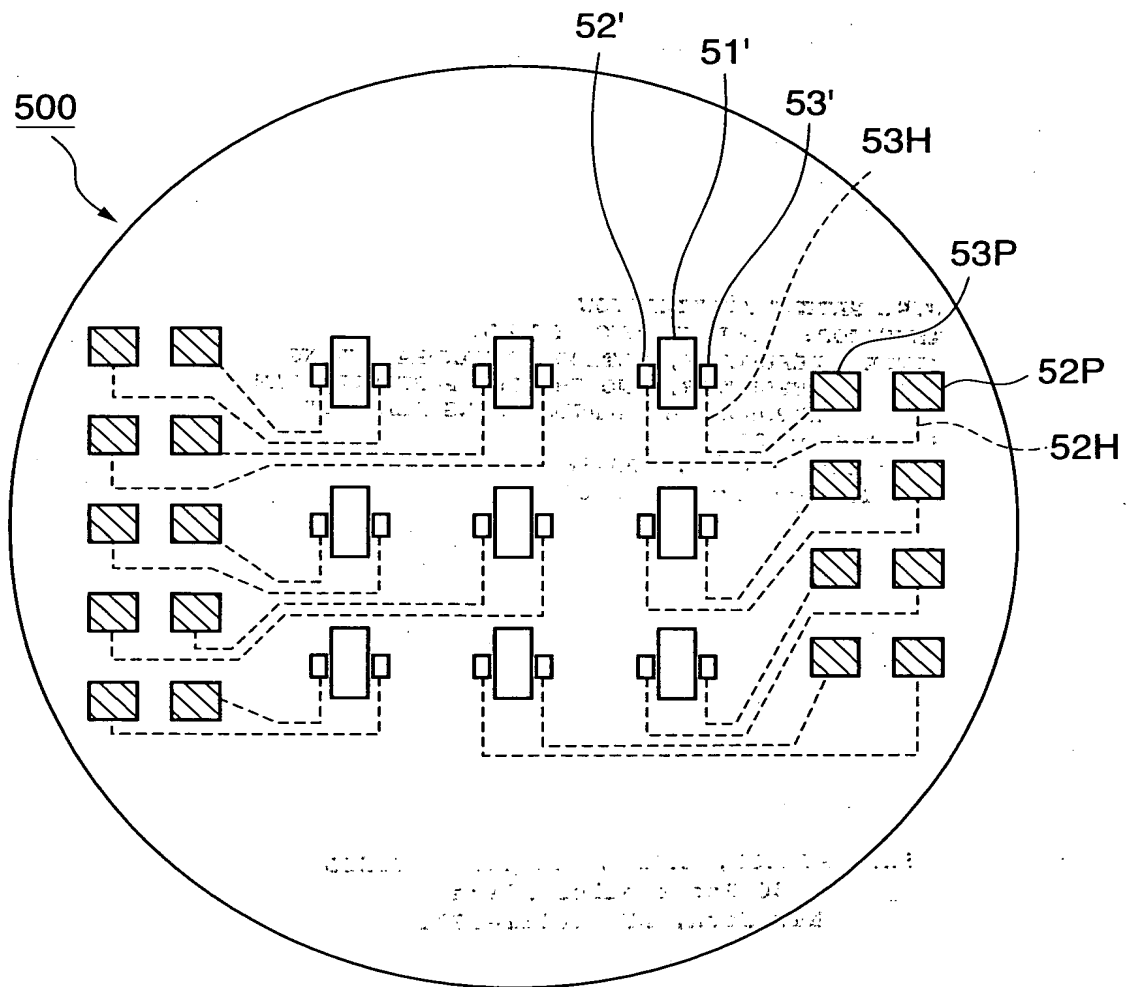
FIG. 5

FIG. 6

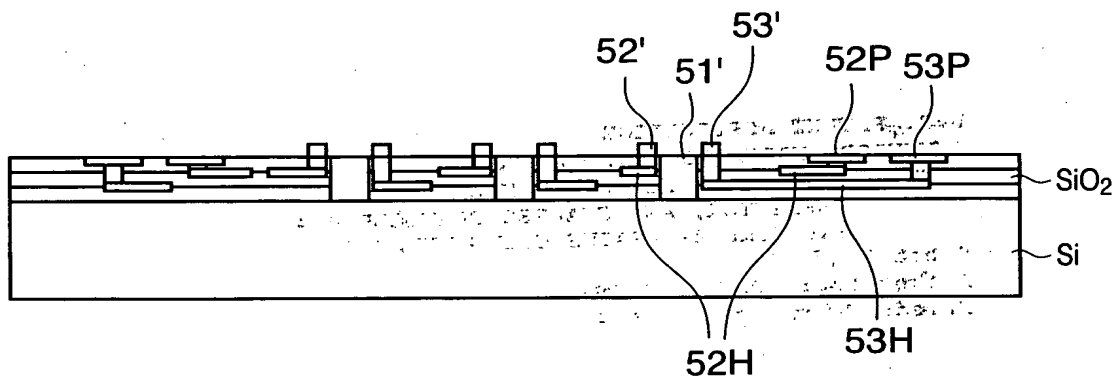


FIG. 7

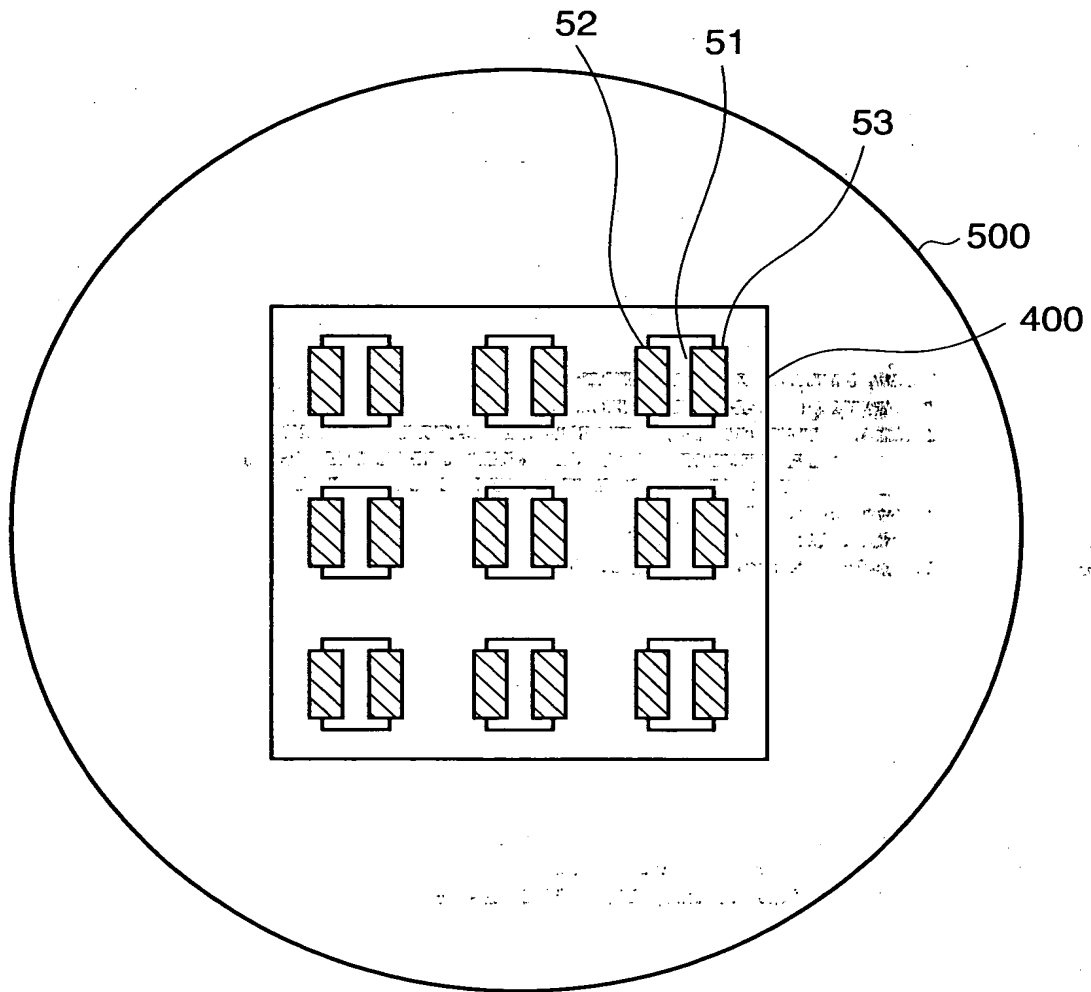


FIG. 8

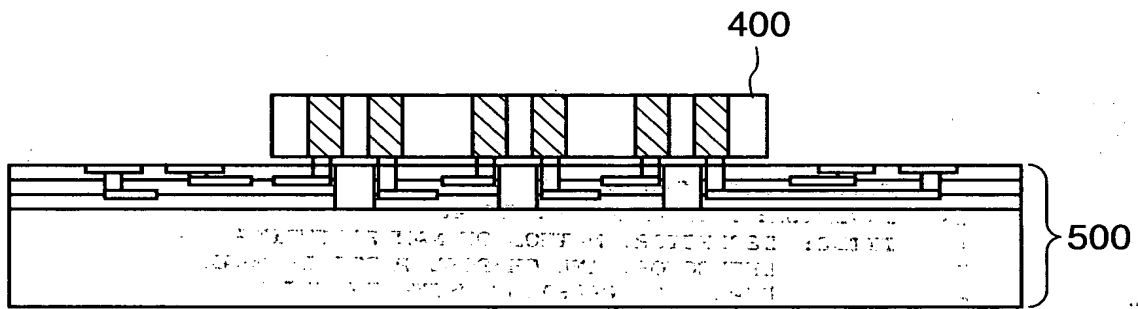
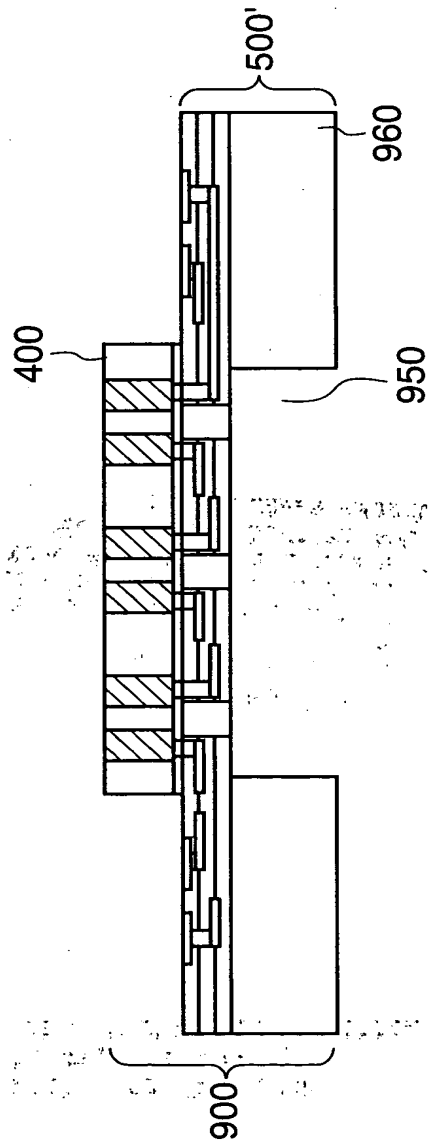


FIG. 8 is a cross-sectional view of the device assembly 100, showing the base layer 500 and the top layer 400. The top layer 400 is positioned on top of the base layer 500. The top layer 400 is a thinner, rectangular block with a series of vertical ridges or fins. The base layer 500 is a thick, rectangular block with a textured surface.

FIG. 9



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FIG. 10

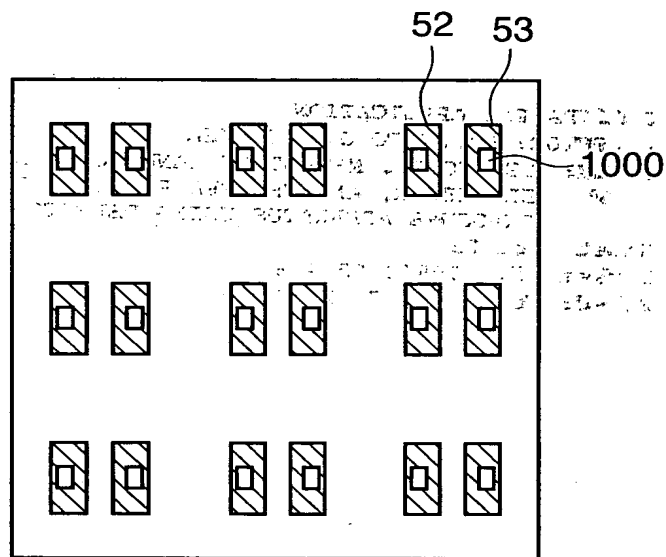


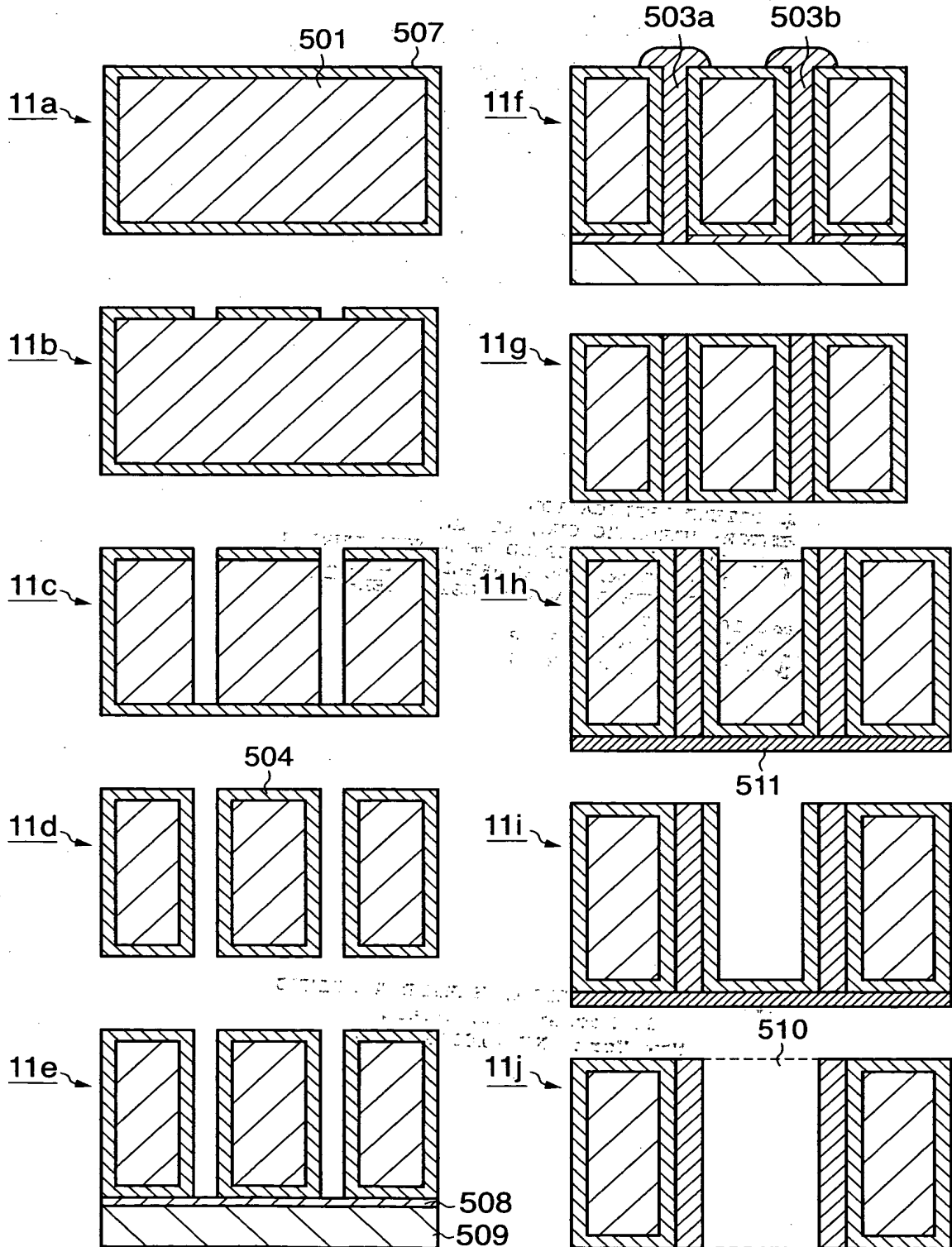
FIG. 11

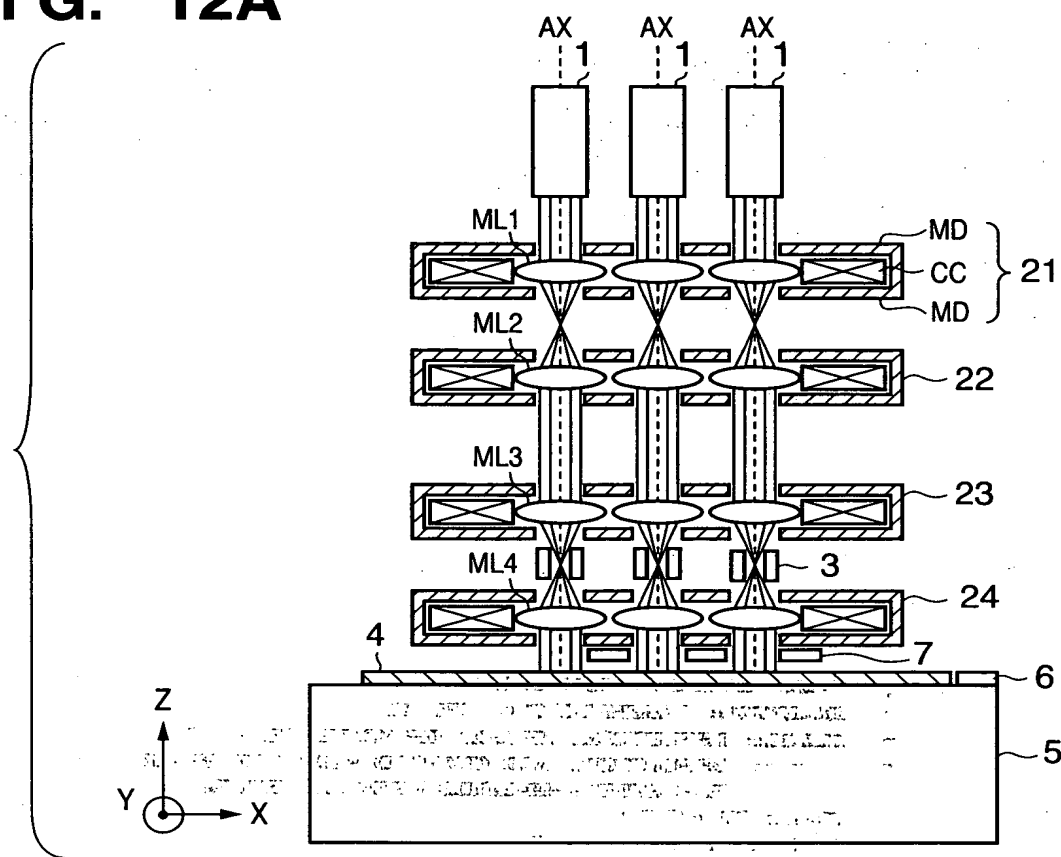
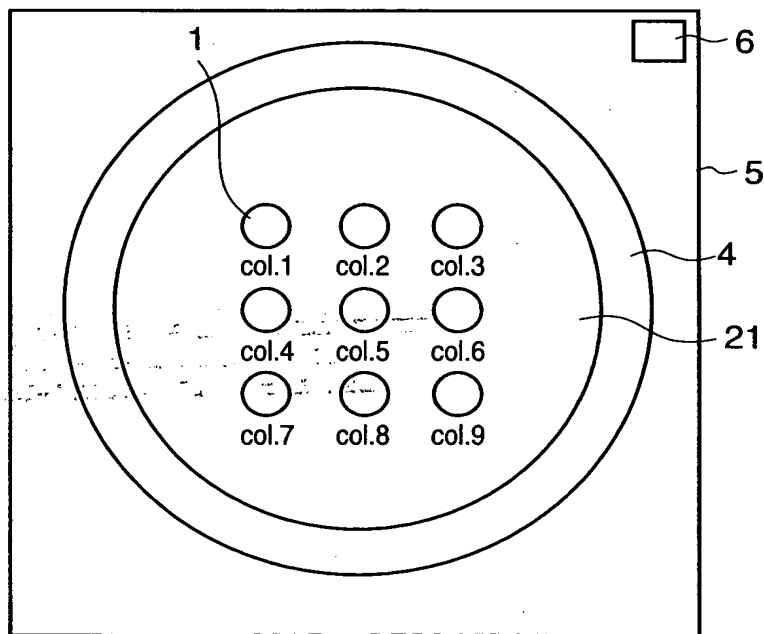
FIG. 12A**FIG. 12B**

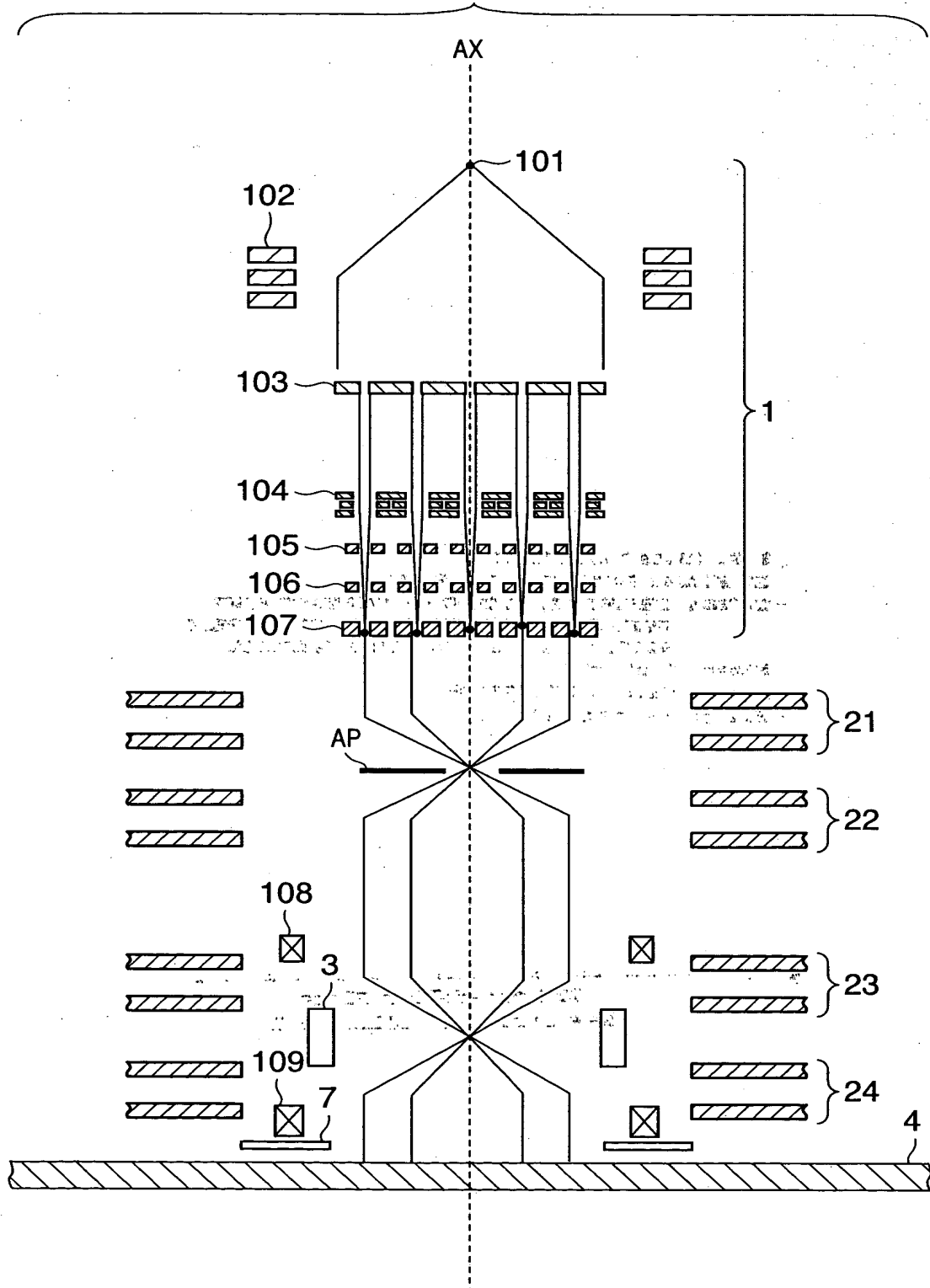
FIG. 13

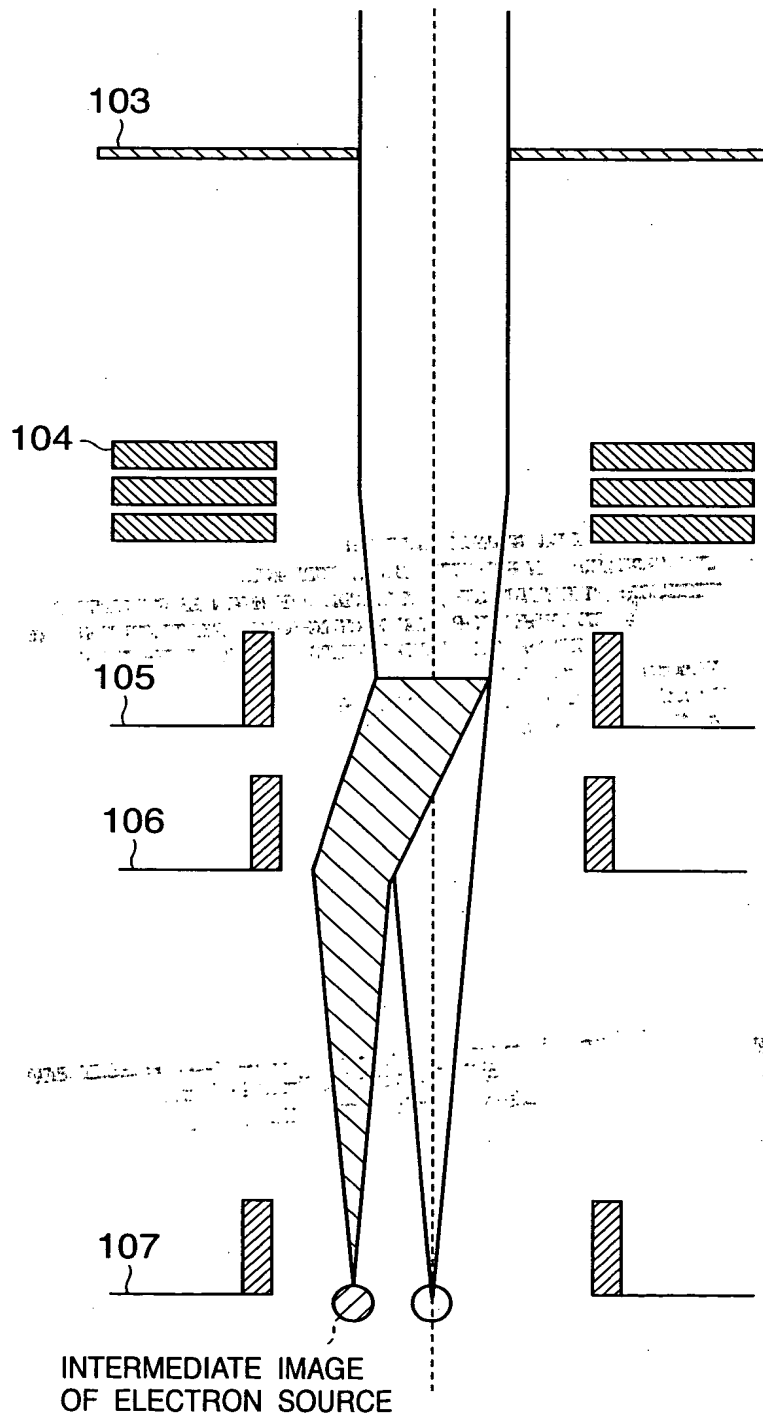
FIG. 14

FIG. 15

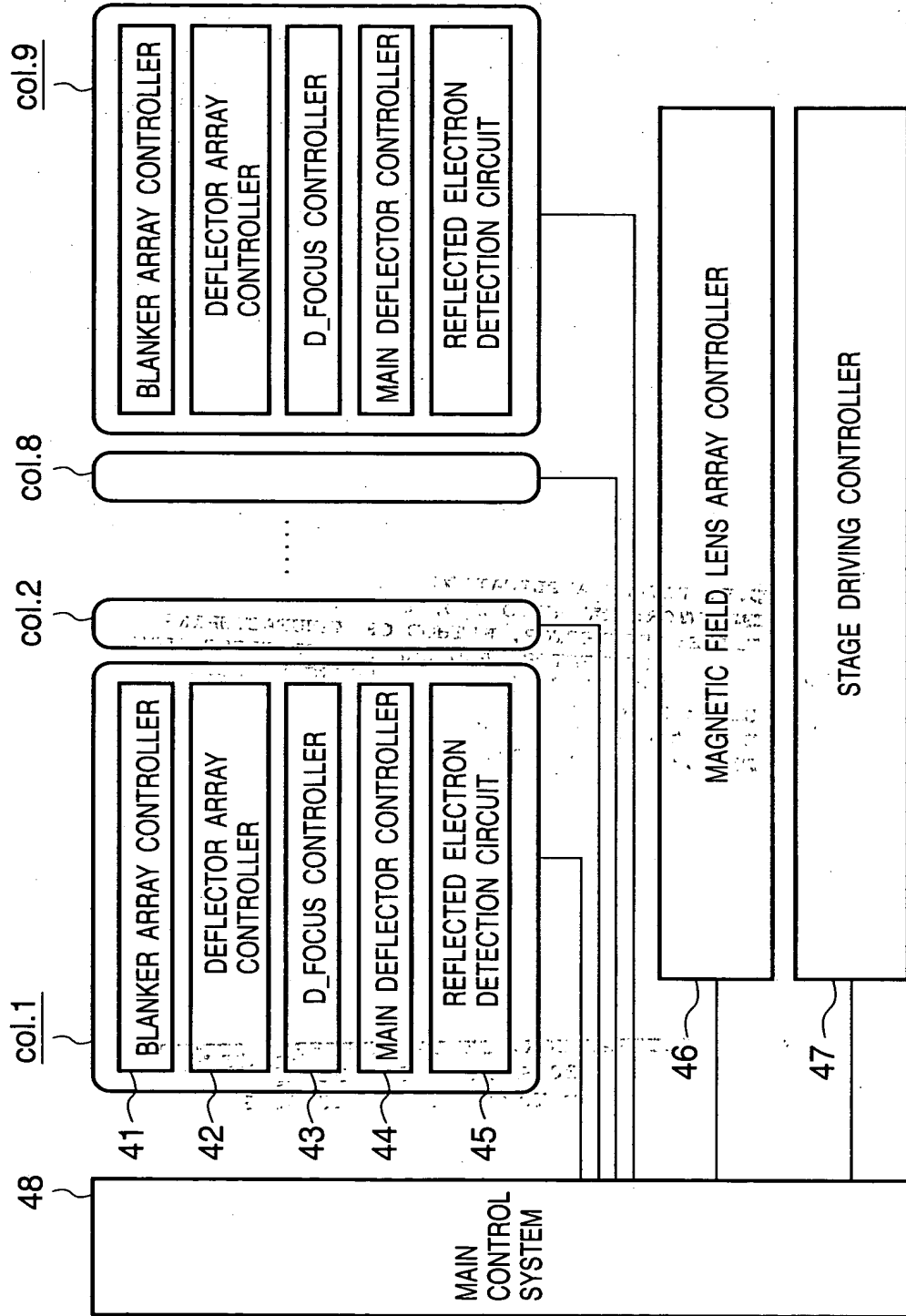


FIG. 16A

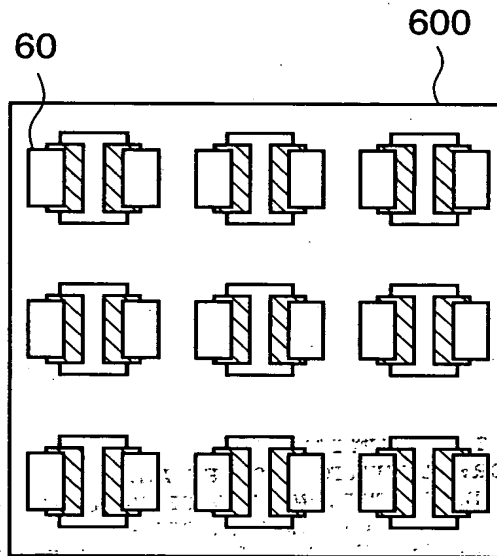


FIG. 16B

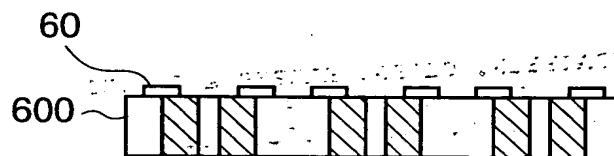


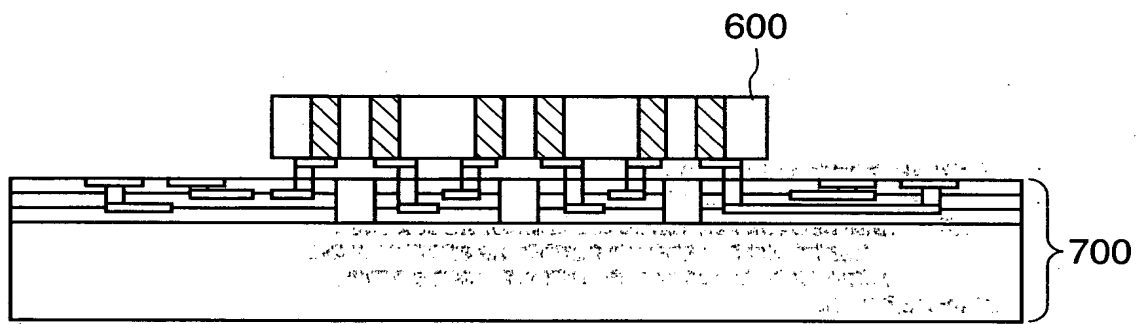
FIG. 17

FIG. 18

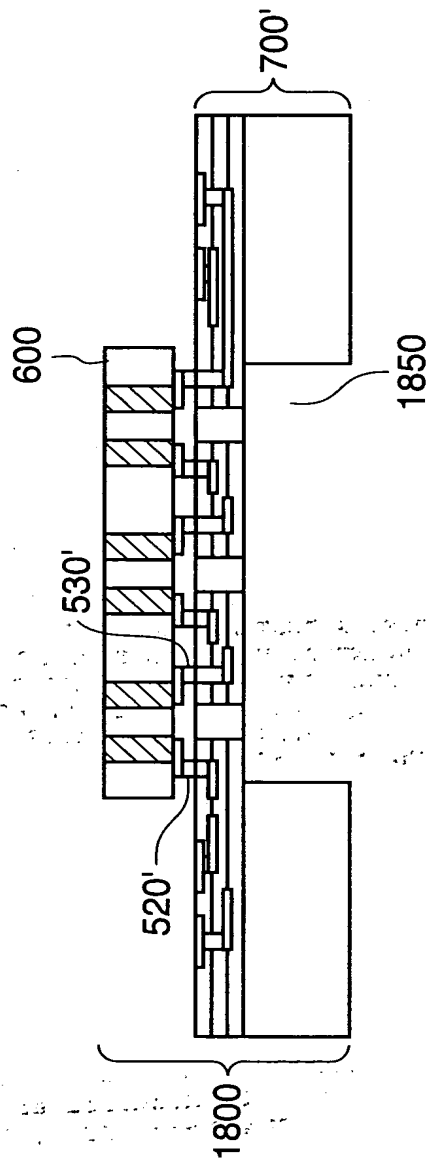


FIG. 19

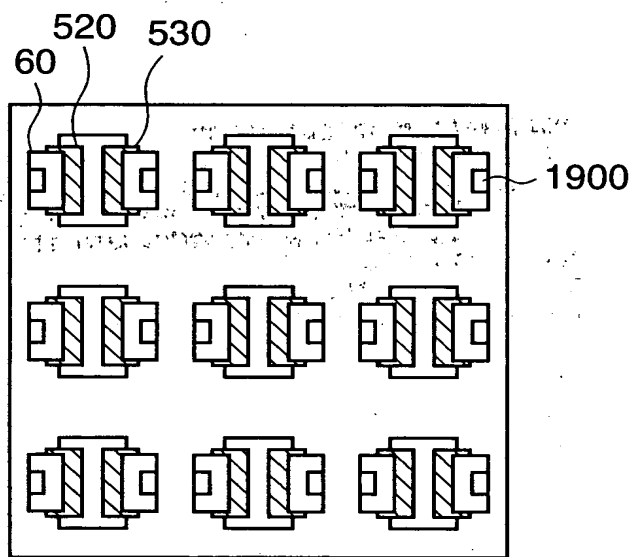


FIG. 20

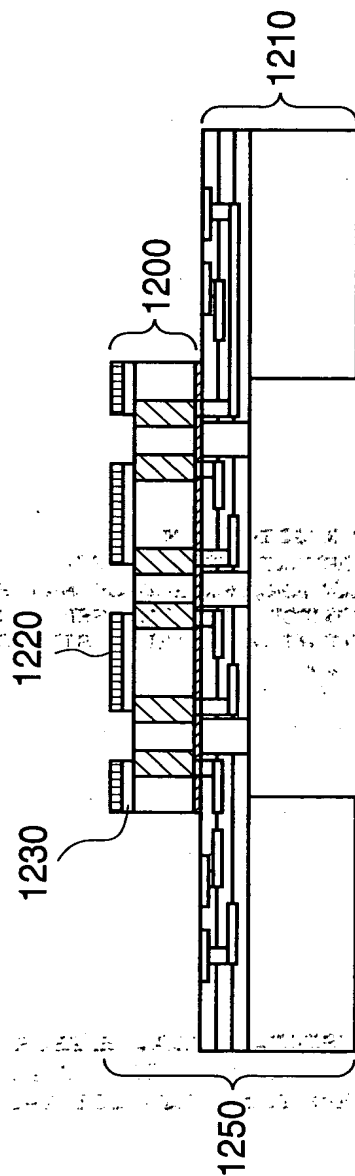
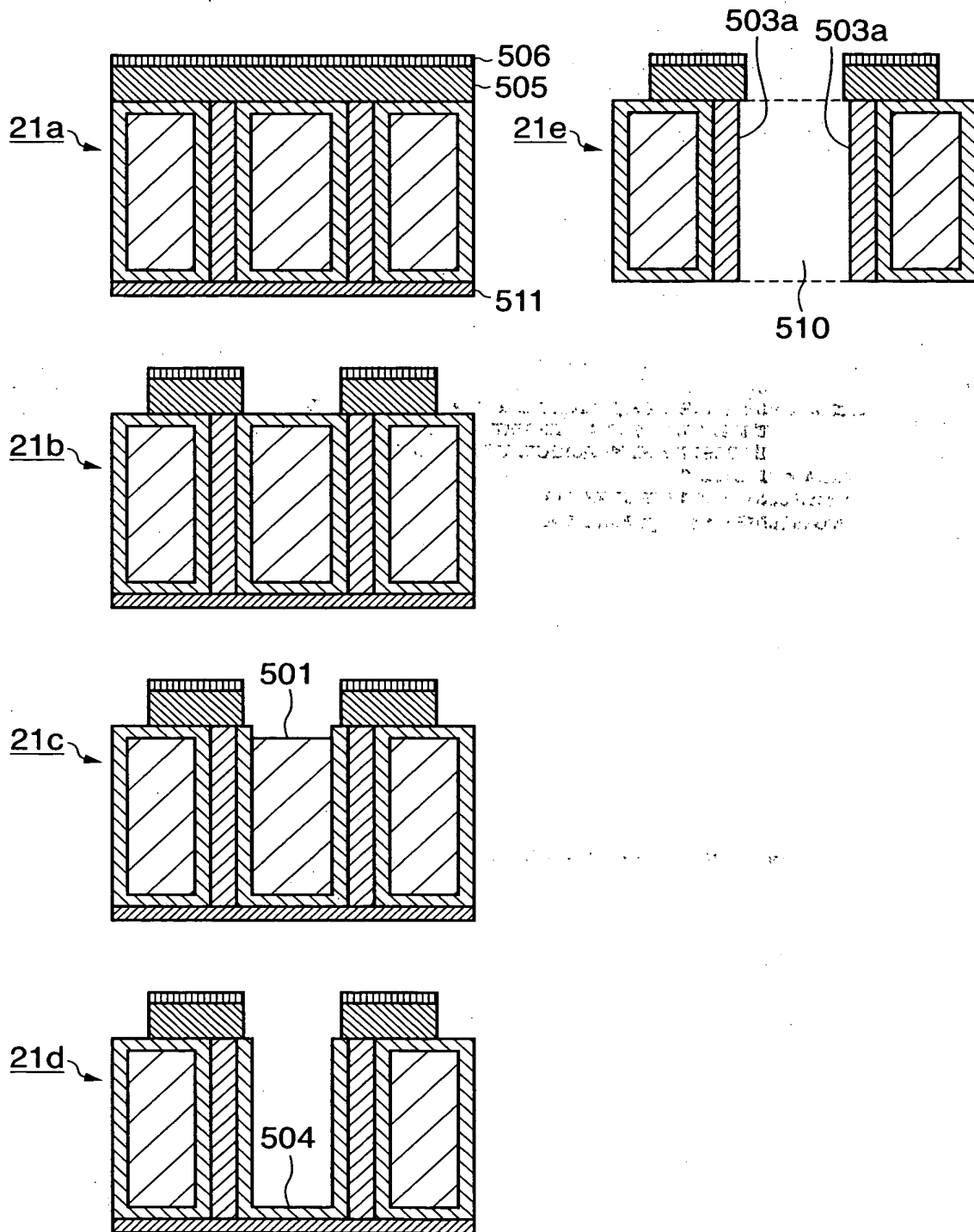


FIG. 21

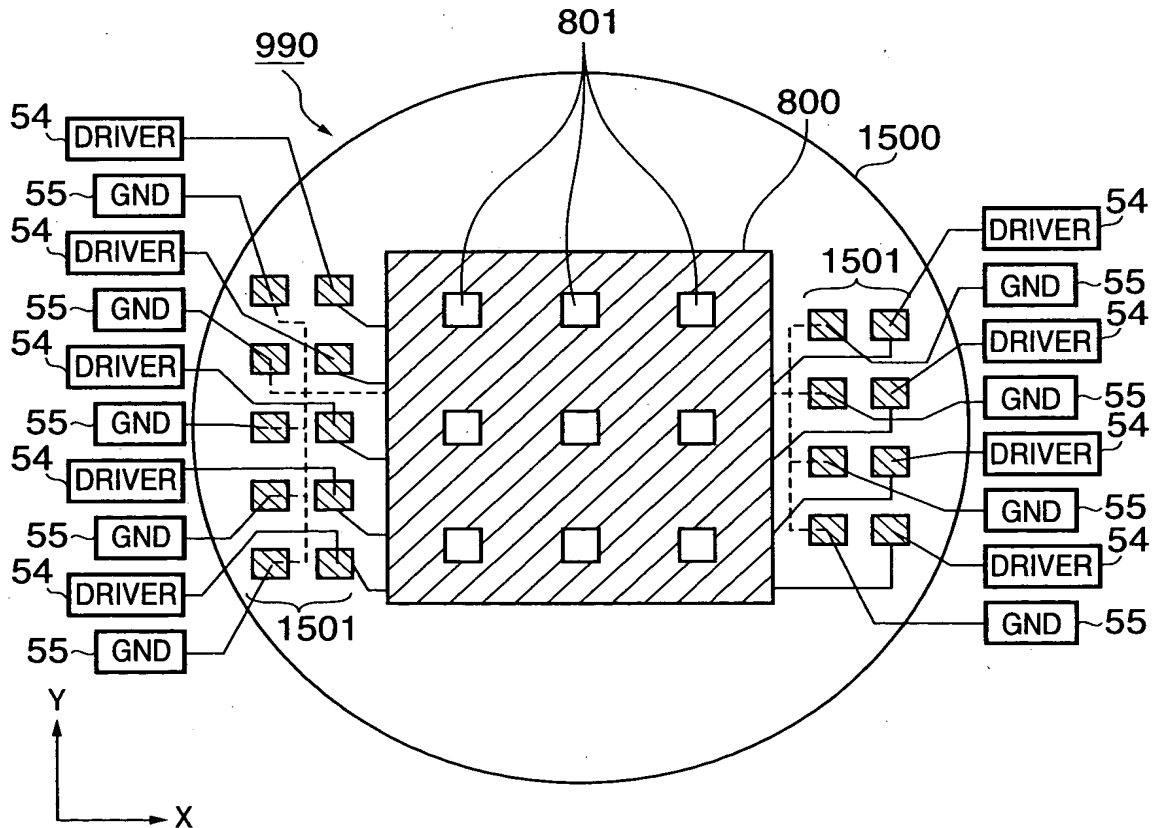


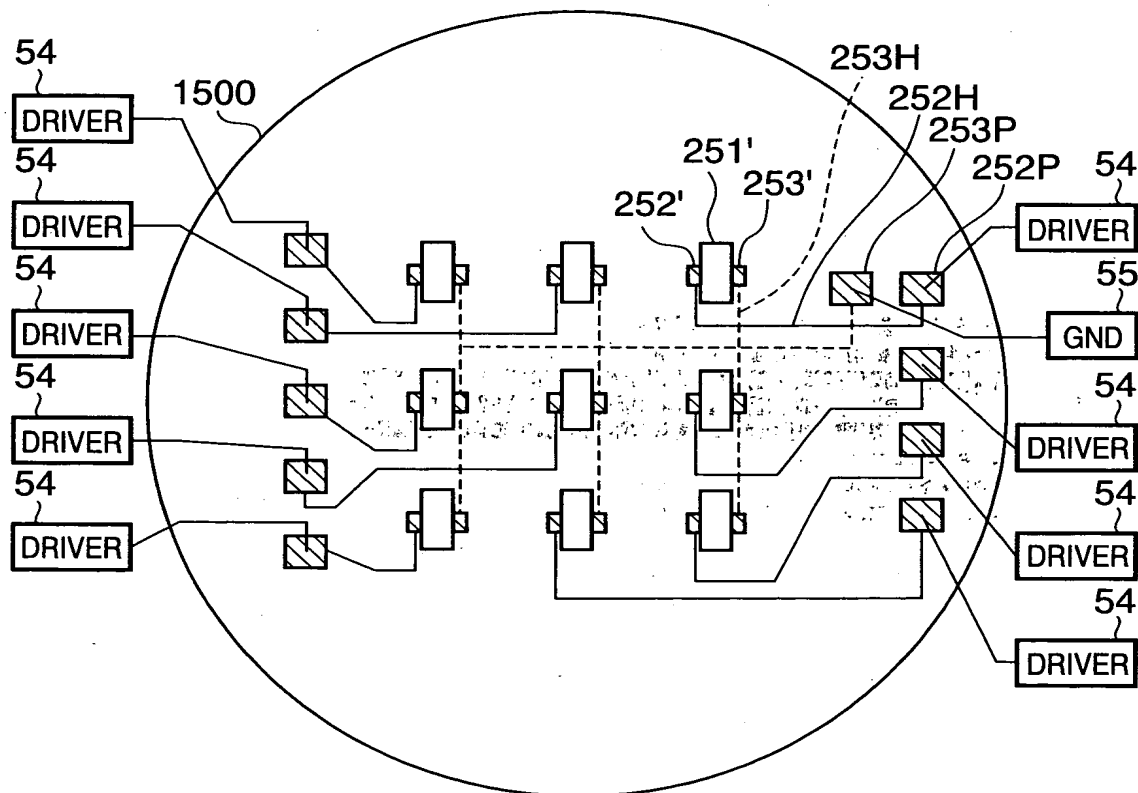
FIG. 23

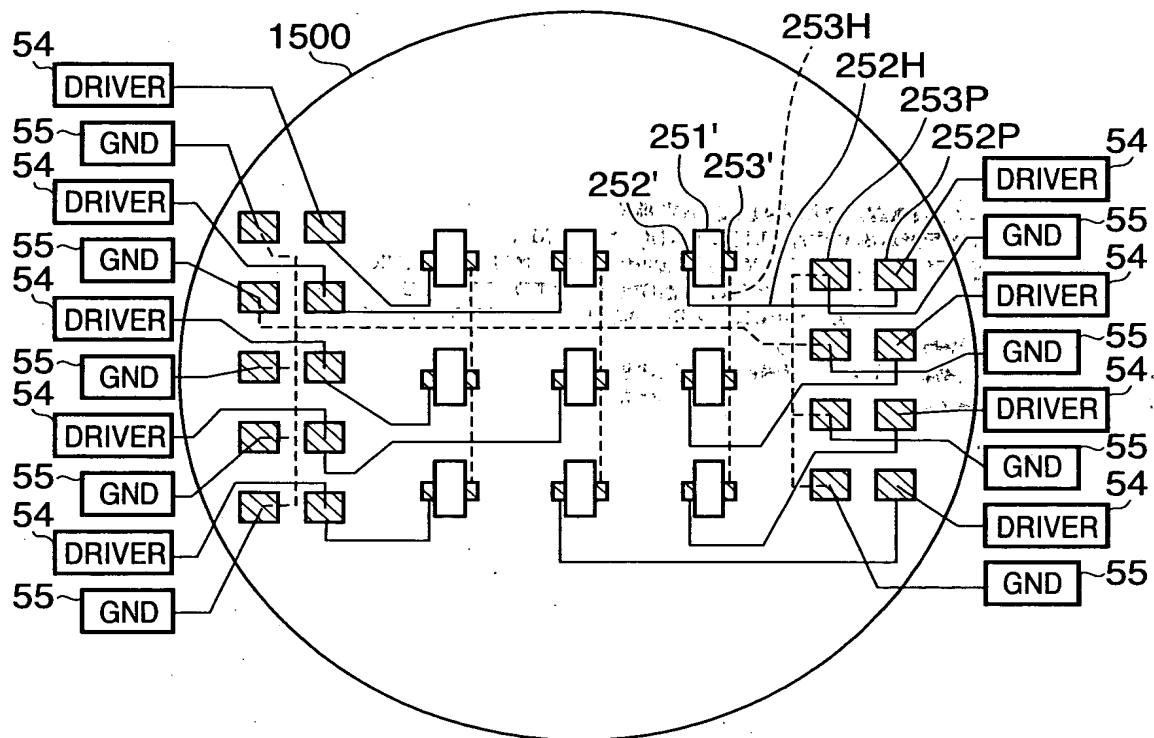
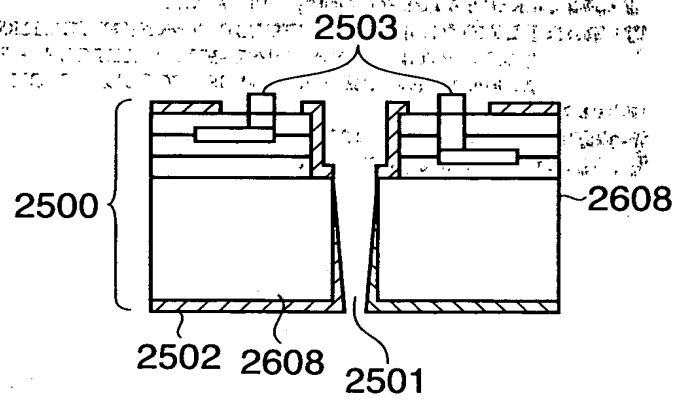
FIG. 24

FIG. 25



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FIG. 26

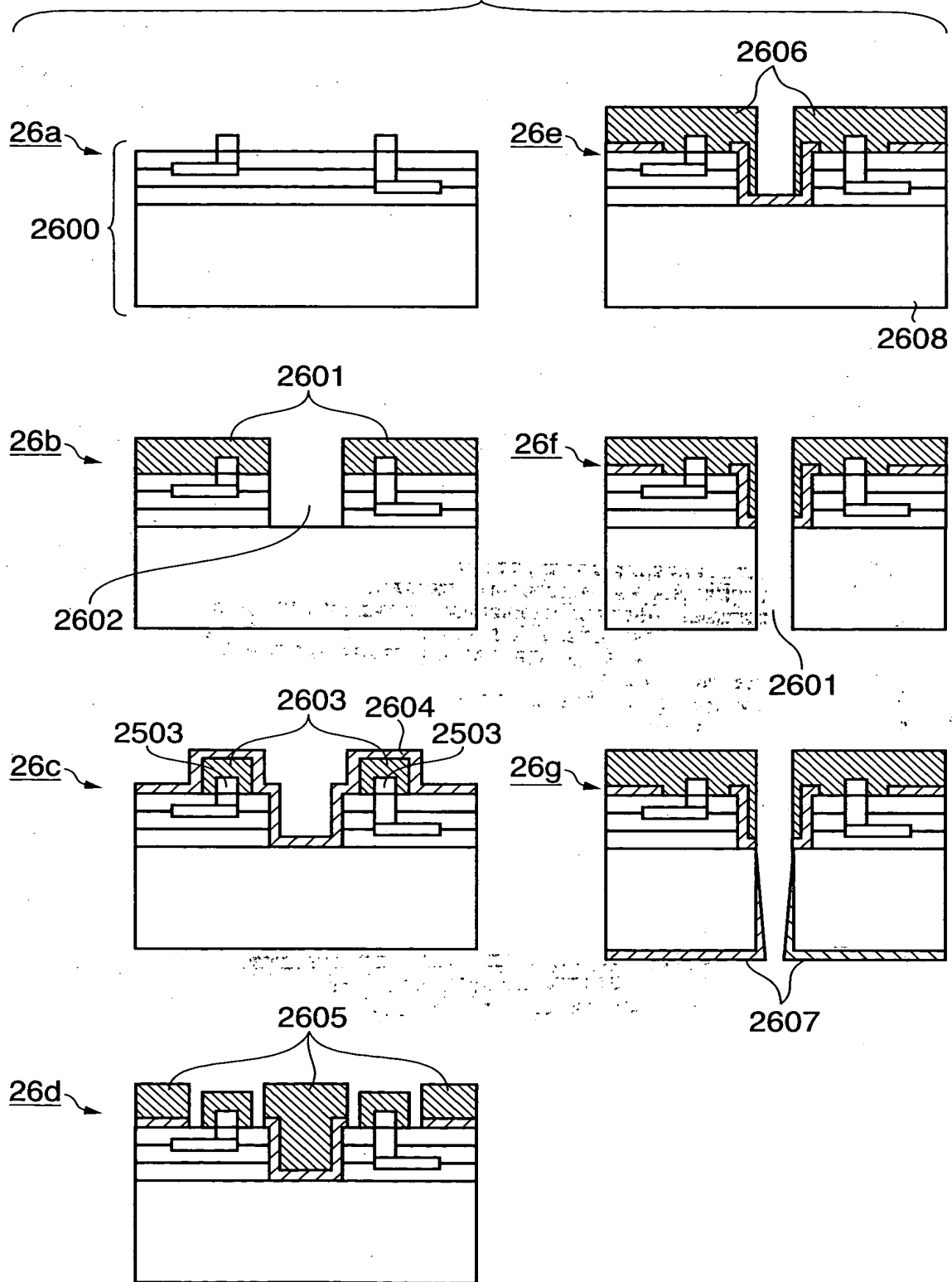


FIG. 27

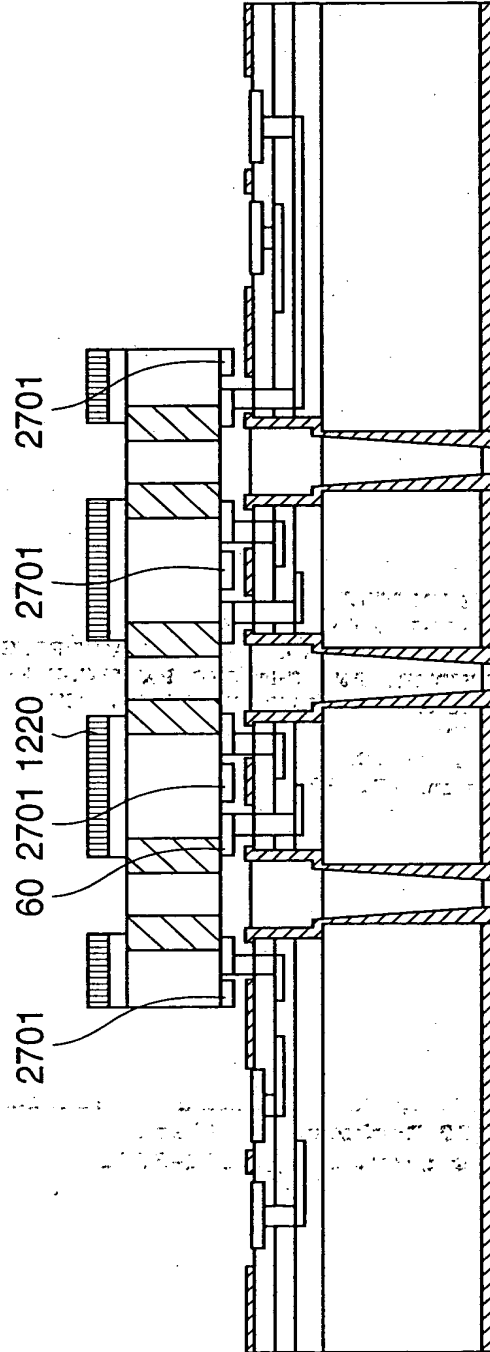


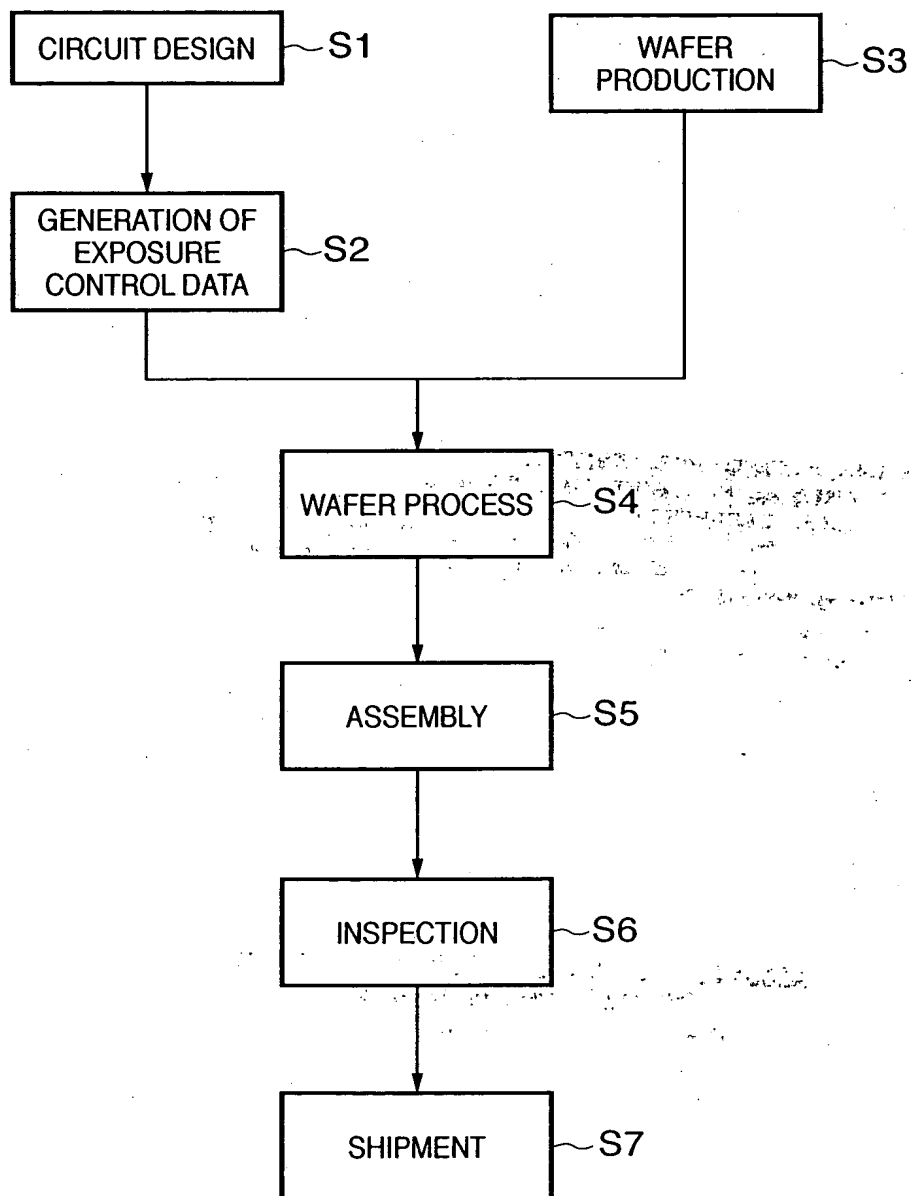
FIG. 28

FIG. 29

